

PACKAGE STRUCTURE AND STACKED PACKAGE MODULE WITH THE SAME

ABSTRACT OF THE DISCLOSURE

A package structure includes two insulation layers, three conductive layers, and two electronic components. The first and second conductive layers are disposed on a top surface and a bottom surface of the first insulation layer, respectively. The second insulation layer is disposed over the first conductive layer. The third conductive layer is disposed on a top surface of the second insulation layer. The first and second electronic components are embedded within the first and second insulation layers, respectively. The first conducting terminals of the first electronic component are electrically connected with the first conductive layer and the second conductive layer through at least one first conductive via and at least one second conductive via. The second conducting terminals of the second electronic component are electrically connected with the first conductive layer and/or electrically connected with the third conductive layer through at least one third conductive via.

Fig 1A